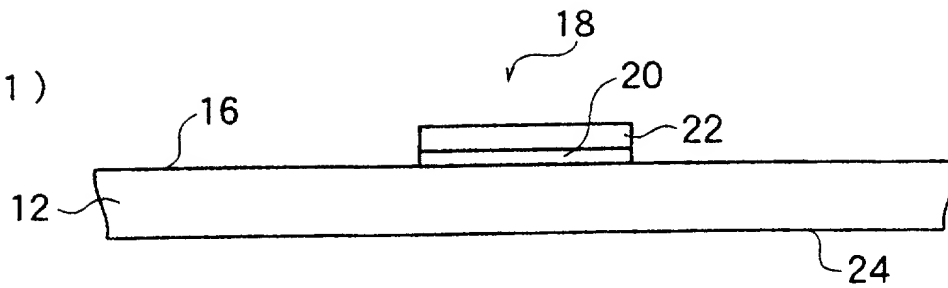
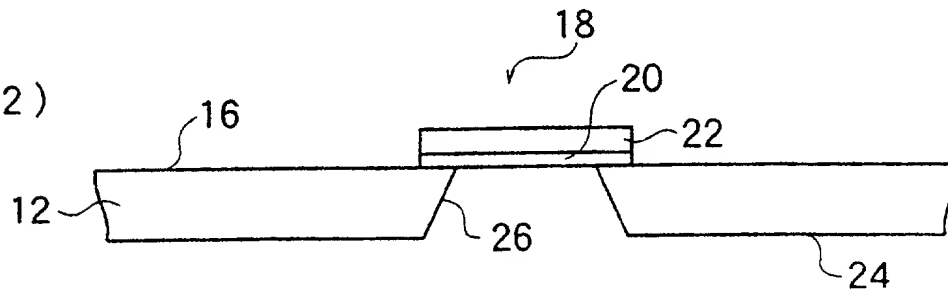


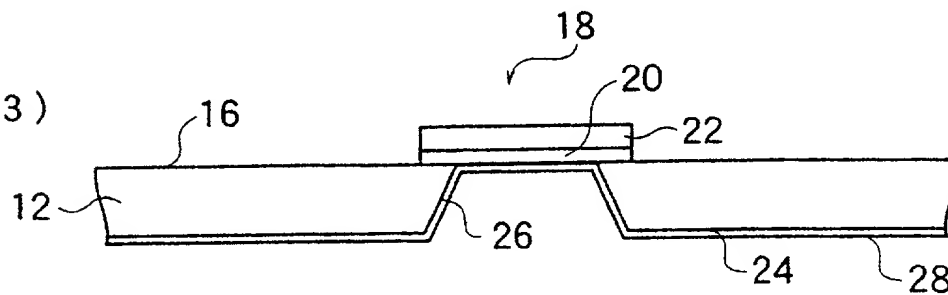
**Fig. 1 (1)**



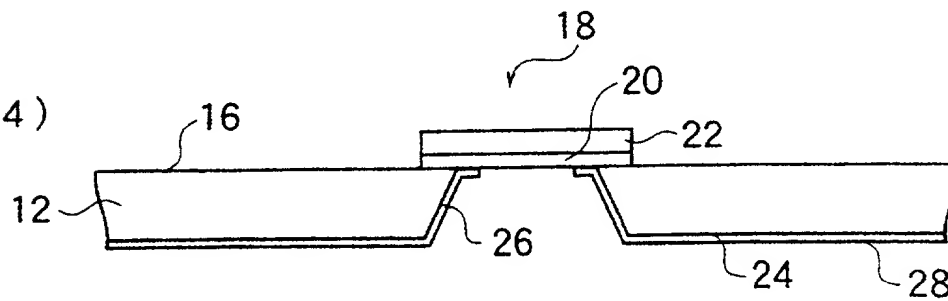
**Fig. 1 (2)**



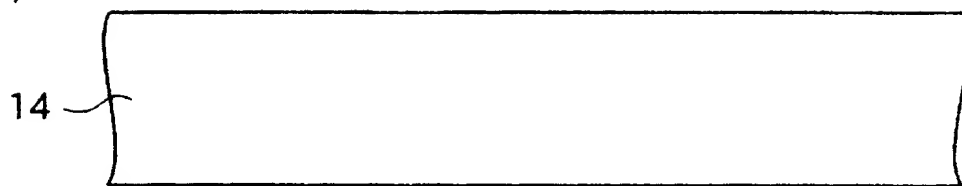
**Fig. 1 (3)**



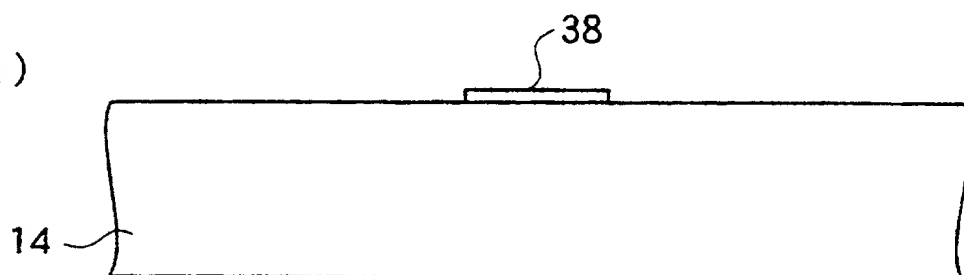
**Fig. 1 (4)**



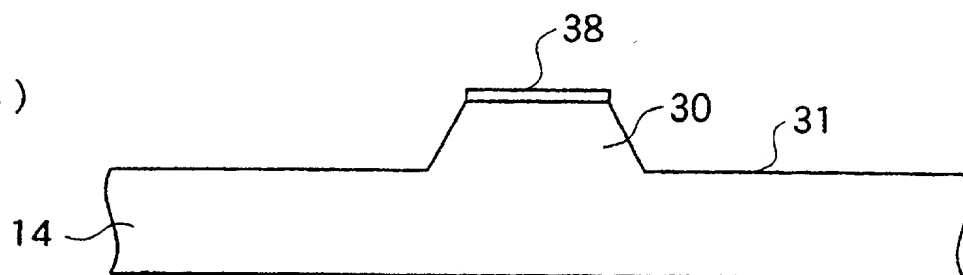
**Fig. 2 (1)**



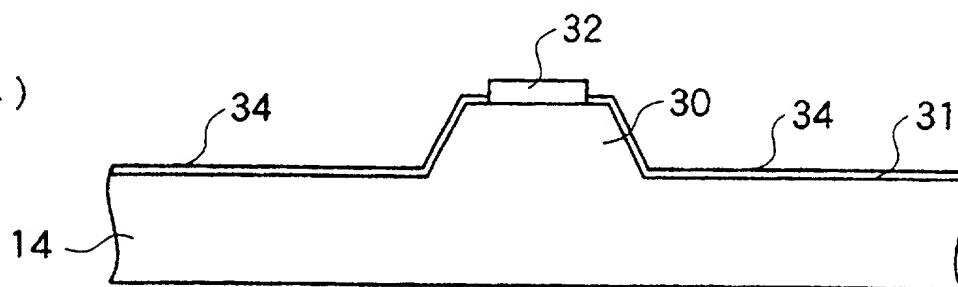
**Fig. 2(2)**



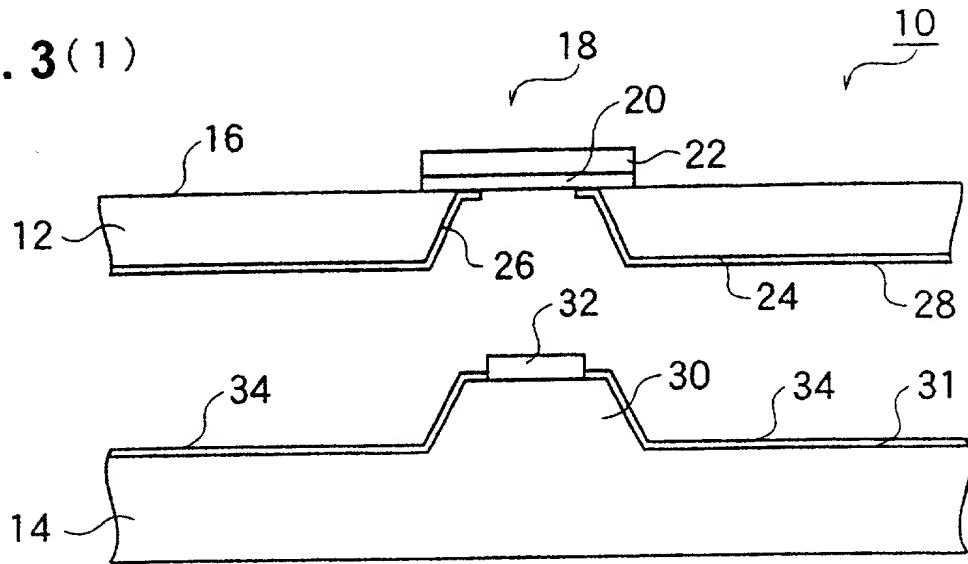
**Fig. 2 (3)**



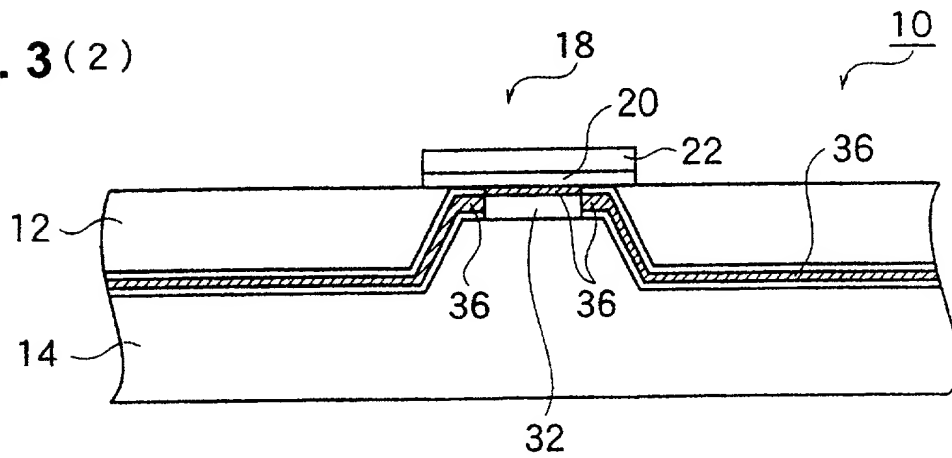
**Fig. 2(4)**



**Fig. 3 (1)**

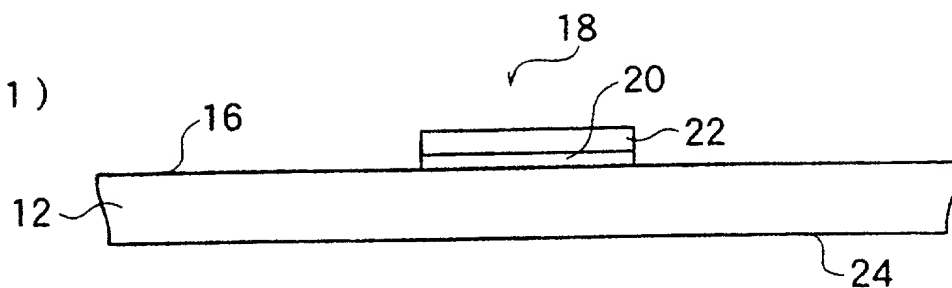


**Fig. 3 (2)**

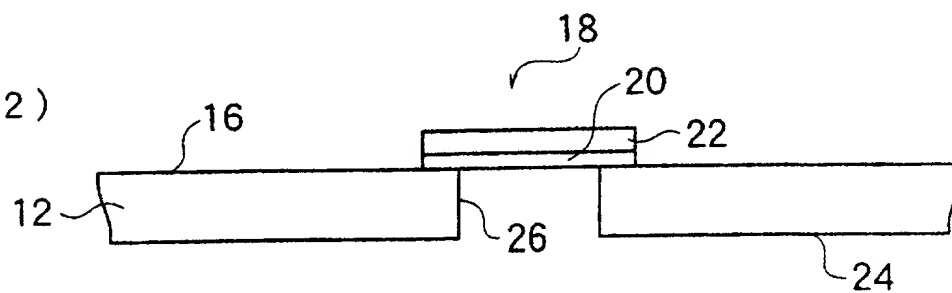


- |                                |                         |
|--------------------------------|-------------------------|
| 10 : Semiconductor device      | 16 : Surface            |
| 12 : First semiconductor chip  | 18 : Electrode          |
| 14 : Second semiconductor chip | 32 : Abutting electrode |

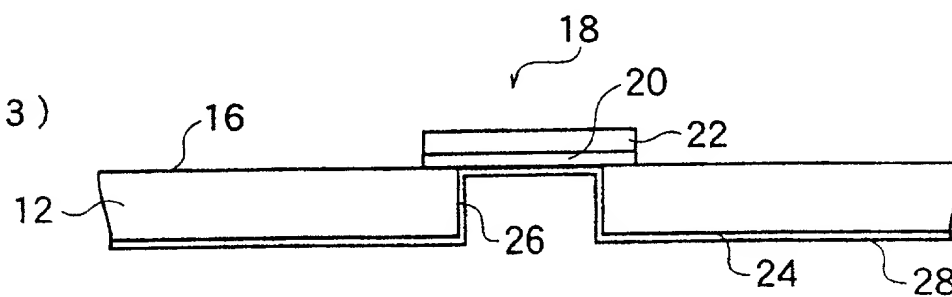
**Fig. 4 (1)**



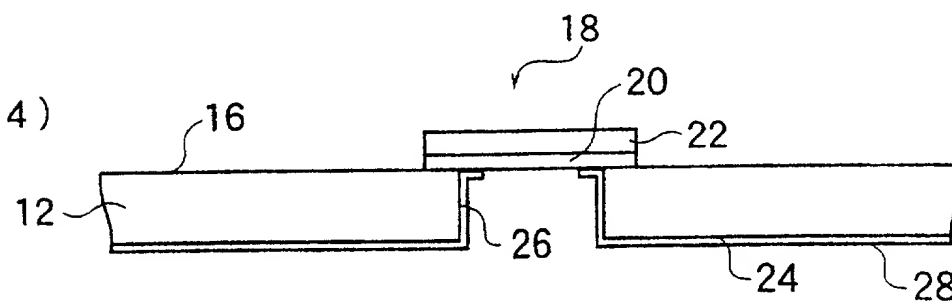
**Fig. 4 (2)**



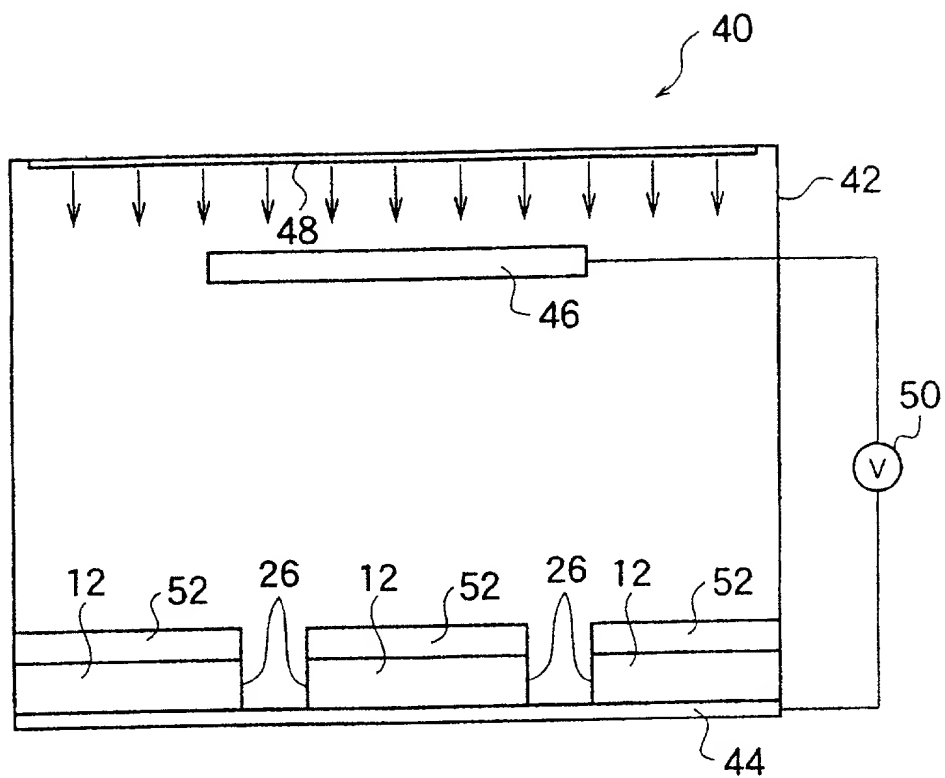
**Fig. 4 (3)**



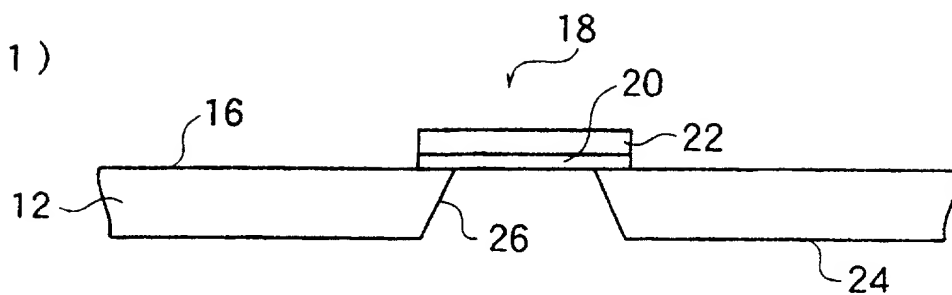
**Fig. 4 (4)**



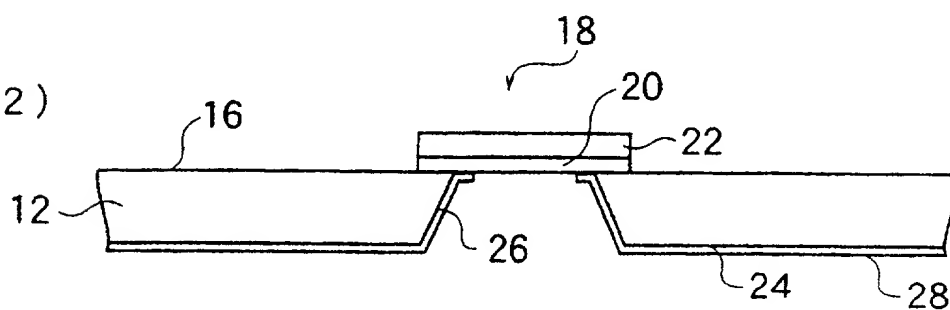
**Fig. 5**



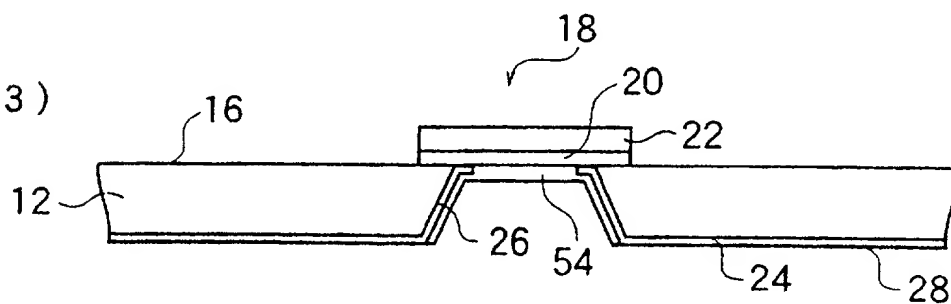
**Fig. 6 (1)**



**Fig. 6 (2)**



**Fig. 6 (3)**



**Fig. 6(4)**

